

30V N-Ch Power MOSFET

V_{DS} 30 V
3.9 m
 $V_{GS}=4.5V$

Part Number	Package	Marking
HTS050N03	SOIC-8	TS050N03

Parameter	Symbol	Conditions	Value	
Continuous Drain Current (Silicon Limited)	I_D	$T_A=25$	20	A
		$T_A=100$	13	
Drain to Source Voltage	V_{DS}	-	30	V
Gate to Source Voltage	V_{GS}	-	± 20	V

Electrical Characteristics at $T_j=25$ (unless otherwise specified)
Static Characteristics

Parameter	Symbol	Conditions	Value			Unit
			min	typ	max	
Drain to Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	30	-	-	V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	1	1.5	3	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{GS}=0V, V_{DS}=20V, T_j=25$	-	-	1	μA
		$V_{GS}=0V, V_{DS}=24V, T_j=125$	-	-	25	
Gate to Source Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	± 100	nA
Drain to Source on Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=20A$	-	3.9	5	m Ω
		$V_{GS}=4.5V, I_D=15A$	-	7.1	9	
Transconductance	g_{fs}	$V_{DS}=5V, I_D=20A$	-	28	-	S
Gate Resistance	R_G	$V_{GS}=0V, V_{DS}$ Open, $f=1MHz$	-	1.3	-	Ω

Dynamic Characteristics

Input Capacitance	C_{iss}	$V_{GS}=0V, V_{DS}=15V, f=1MHz$	-	2935	-	pF
Output Capacitance	C_{oss}		-	217	-	
Reverse Transfer Capacitance	C_{rss}		-	142	-	
Total Gate Charge (10V)	$Q_g(10V)$	$V_{DD}=15V, I_D=20A, V_{GS}=10V$	-	52	-	nC
Total Gate Charge (4.5V)	$Q_g(4.5V)$		-	32	-	
Gate to Source Charge	Q_{gs}		-	5.7	-	
Gate to Drain (Miller) Charge	Q_{gd}		-	7.2	-	
Turn on Delay Time	$t_{d(on)}$	$V_{DD}=15V, I_D=1A, V_{GS}=10V, R_G=2.7\Omega,$	-	25	-	ns
Rise time	t_r		-	20	-	
Turn off Delay Time	$t_{d(off)}$		-	70	-	
Fall Time	t_f		-	20	-	

Reverse Diode Characteristics

Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_F=10A$	-		1.2	V
Reverse Recovery Time	t_{rr}	$I_F=10A, di_F/dt=100A/\mu s$	-	35	-	ns
Reverse Recovery Charge	Q_{rr}		-	15	-	nC



Fig 1. Typical Output Characteristics	Figure 2. On-Resistance vs. Gate-Source Voltage
Figure 3. On-Resistance vs. Drain Current and Gate Voltage	Figure 4. Normalized On-Resistance vs. Junction Temperature
Figure 5. Typical Transfer Characteristics	Figure 6. Typical Source-Drain Diode Forward Voltage

Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

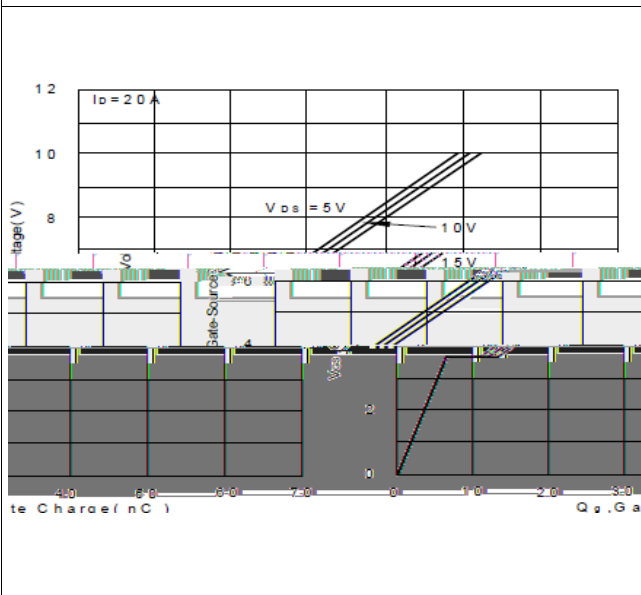


Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

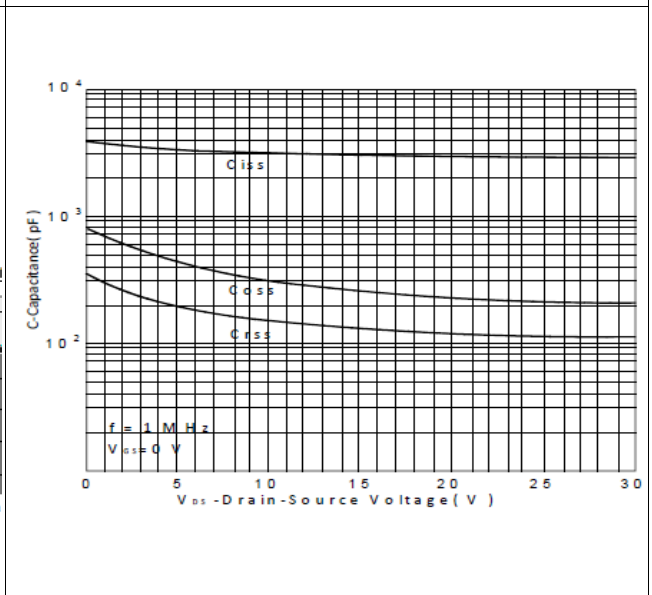


Figure 9. Maximum Safe Operating Area

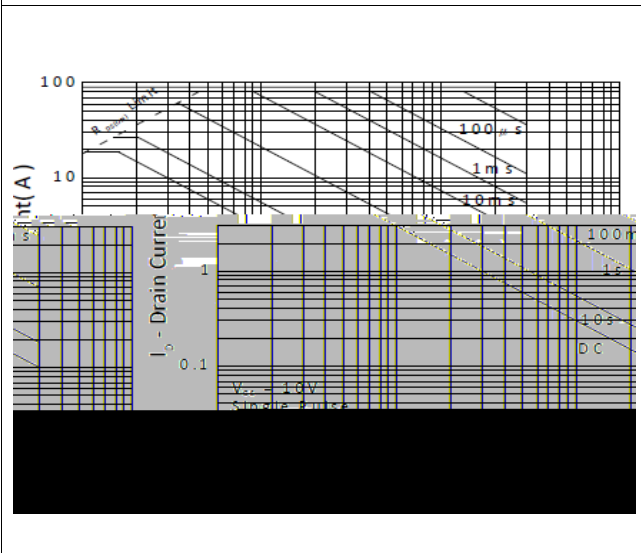


Figure 10. Single Pulse Maximum Power Dissipation

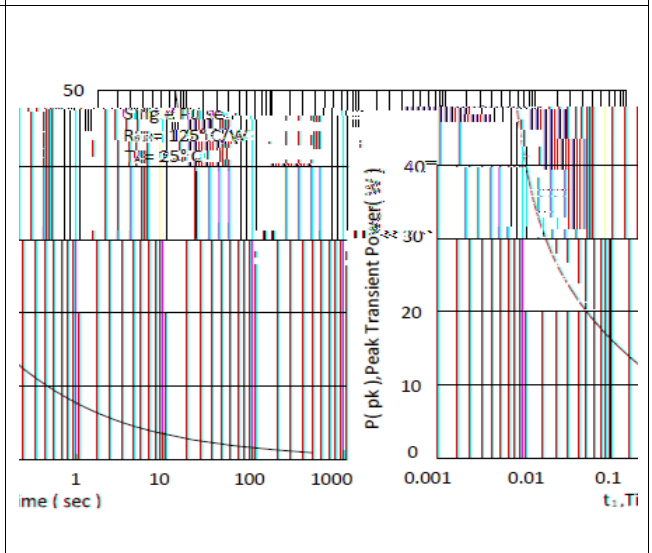
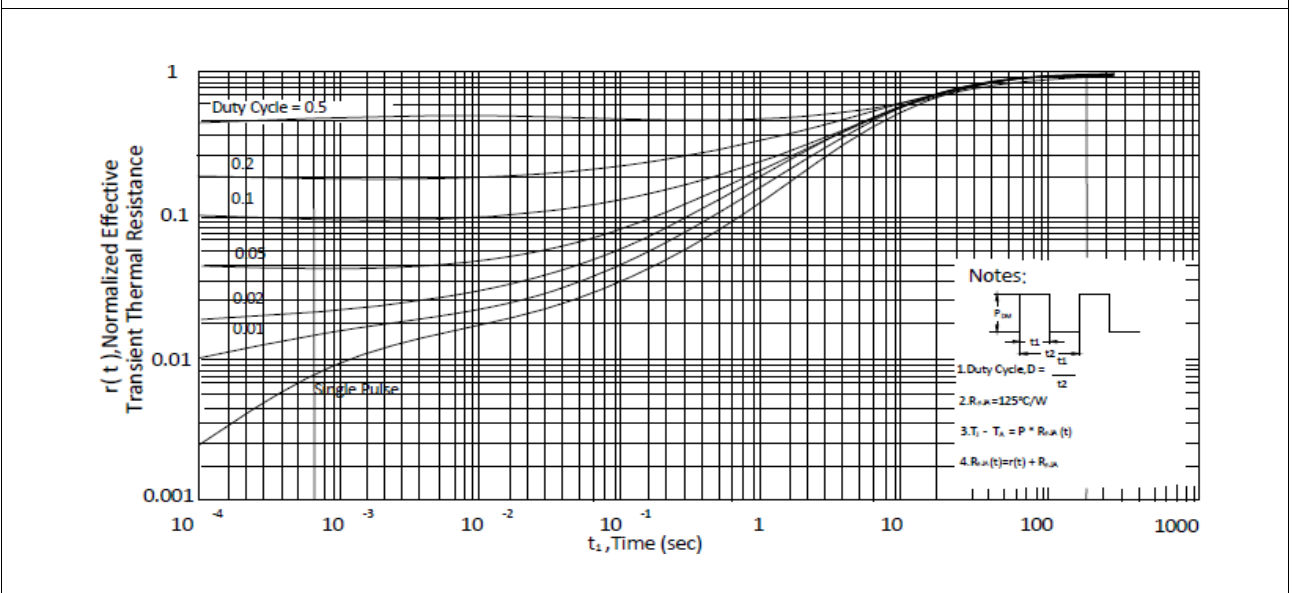


Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Case



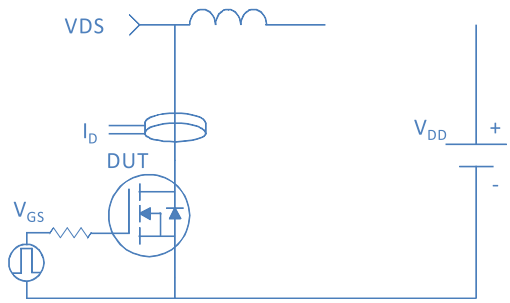
Inductive switching Test

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Gate Charge Test

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Uclamped Inductive Switching (UIS) Test

	
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Diode Recovery Test

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SOIC-8, 8 leads